

InGaAsP MQW DC-PBH PULSED LASER DIODE MODULE
1 310 nm OTDR APPLICATION

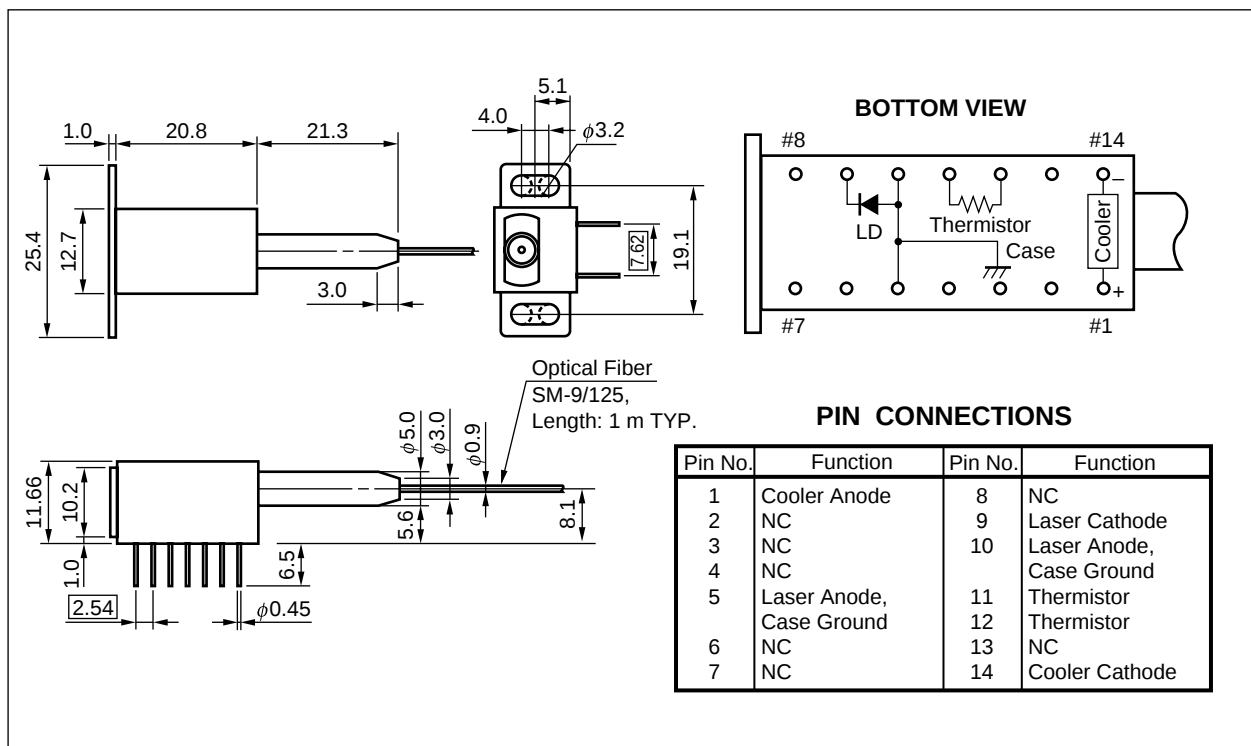
DESCRIPTION

The NX7361JB-BC is a 1 310 nm Multiple Quantum Well (MQW) structure pulsed laser diode DIP module with single mode fiber and internal thermoelectric cooler. It is designed for light sources of optical measurement equipment (OTDR).

FEATURES

- High output power $P_r = 150 \text{ mW MIN. @ } I_{FP} = 1\,000 \text{ mA, PW} = 10 \mu\text{s, Duty} = 1\%$
- Long wavelength $\lambda_c = 1\,310 \text{ nm}$
- Internal thermoelectric cooler, thermistor
- Hermetically sealed 14-pin Dual-In-Line Package
- Single mode fiber pigtail

★ PACKAGE DIMENSIONS (UNIT: mm)



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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

★ ORDERING INFORMATION

Part Number	Available Connector
NX7361JB-BC	With FC-UPC Connector

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ratings	Unit
Pulsed Forward Current ^{*1}	I _{FP}	1.2	A
Reverse Voltage	V _R	2.0	V
Cooler Current	I _C	1.0	A
Cooler Voltage	V _C	2.0	V
Thermistor Current	I _t	0.5	mA
Thermistor Voltage	V _t	12.0	V
Operating Case Temperature	T _C	−20 to +65	°C
Storage Temperature	T _{stg}	−40 to +70	°C
Lead Soldering Temperature	T _{sld}	260 (10 sec)	°C

*1 Pulse conditions: Pulse width (PW) = 10 μs, Duty = 1%

ELECTRO-OPTICAL CHARACTERISTICS (T_{LD} = 25°C, T_C = -20 to +65°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Forward Voltage	V _{FP}	CW, I _F = 30 mA		2.5	4.0	V
Threshold Current	I _{th}	CW		35	65	mA
Optical Output Power from Fiber	P _r	I _{FP} = 1 000 mA, *1	150			mW
		I _{FP} = 600 mA, *1	90			
		I _{FP} = 400 mA, *1	40			
Center Wavelength	λ _c	RMS, I _{FP} = 400, 600, 1 000 mA, *1	1 290	1 310	1 330	nm
Spectral Width	σ	RMS, I _{FP} = 400, 600, 1 000 mA, *1		3.0	7.0	nm
Rise Time	t _r	10-90%		1.0	2.0	ns
Fall Time	t _f	90-10%		1.4	2.0	ns

*1 PW = 10 μs, Duty = 1%

ELECTRO-OPTICAL CHARACTERISTICS

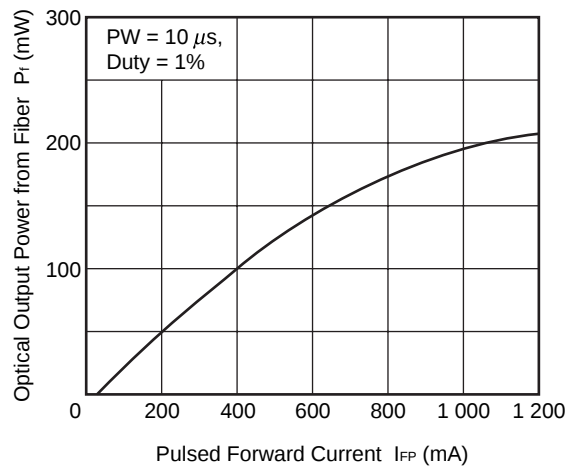
(Applicable to Thermistor and TEC: T_{LD} = 25°C, T_C = -20 to +65°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Thermistor Resistance	R	T _{LD} = 25°C	9.5	10.0	10.5	kΩ
B Constant	B		3 350	3 450	3 550	K
Cooler Current	I _c	ΔT = 40°C		0.6	0.8	A
Cooler Voltage	V _c	ΔT = 40°C		1.1	1.5	V
Cooling Capacity	ΔT ^{*1}	I _c = 0.8 A	40			°C

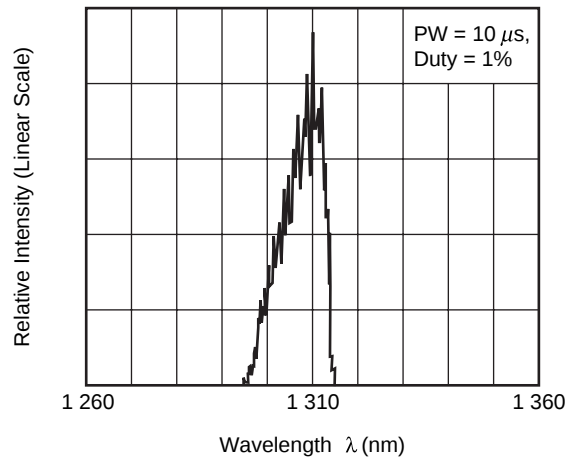
*1 ΔT = |T_C - T_{LD}|

★ TYPICAL CHARACTERISTICS (T_c = 25°C, unless otherwise specified)

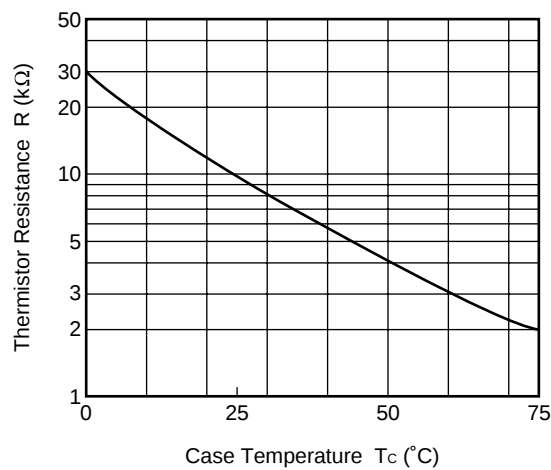
OPTICAL OUTPUT POWER FROM FIBER vs.
PULSED FORWARD CURRENT



SPECTRUM



THERMISTOR RESISTANCE vs.
CASE TEMPERATURE



Remark The graphs indicate nominal characteristics.

★ OTDR LD FAMILY

Part Number	Electro-Optical Characteristics (T _c = 25°C)			Conditions			Application	Package
	λ_c (nm)	P _f (mW)		I _{FP} (mA)	PW (μ s)	Duty (%)		
	TYP.	MIN.	TYP.					
NX7327BF-AA	1 310	110	180	1 000	10	1	OTDR	4-pin coax. with SMF
NX7328BF-AA	1 310	70	110	400	10	1	OTDR	4-pin coax. with SMF
NX7329BB-AA	1 310	25	50	400	10	1	OTDR	4-pin coax. with SMF
NX7361JB-BC	1 310	150	–	1 000	10	1	OTDR	14-pin DIP with SMF
NX7526BF-AA	1 550	95	145	1 000	10	1	OTDR	4-pin coax. with SMF
NX7527BF-AA	1 550	120	145	1 000	10	1	OTDR	4-pin coax. with SMF
NX7528BF-AA	1 550	60	80	400	10	1	OTDR	4-pin coax. with SMF
NX7529BB-AA	1 550	20	40	400	10	1	OTDR	4-pin coax. with SMF
NX7561JB-BC	1 550	135	–	1 000	10	1	OTDR	14-pin DIP with SMF
NX7661JB-BC	1 625	120	–	1 000	10	1	OTDR	14-pin DIP with SMF

REFERENCE

Document Name	Document No.
Optical semiconductor devices for fiberoptic communications Selection Guide	P12480E
Opto-Electronics Devices Pamphlet	P13623E
Opto-Electronics Devices (CD-ROM)	P12944X
NEC semiconductor device reliability/quality control system ^{*1}	C11159E
Quality grades on NEC semiconductor devices ^{*1}	C11531E
SEMICONDUCTOR SELECTION GUIDE –Products and Packages– ^{*1}	X13769E

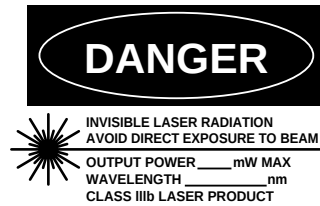
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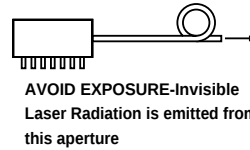
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SAFETY INFORMATION ON THIS PRODUCT



SEMICONDUCTOR LASER



Warning	Laser Beam	A laser beam is emitted from this diode during operation. The laser beam, visible or invisible, directly or indirectly, may cause injury to the eye or loss of eyesight. - Do not look directly into the laser beam. - Avoid exposure to the laser beam, any reflected or collimated beam.
Caution	GaAs Products	The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested. - Do not destroy or burn the product. - Do not cut or cleave off any part of the product. - Do not crush or chemically dissolve the product. - Do not put the product in the mouth. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.
Caution	Optical Fiber	A glass-fiber is attached on the product. Handle with care. When the fiber is broken or damaged, handle carefully to avoid injury from the damaged part or fragments.

► Business issue

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► Technical issue

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